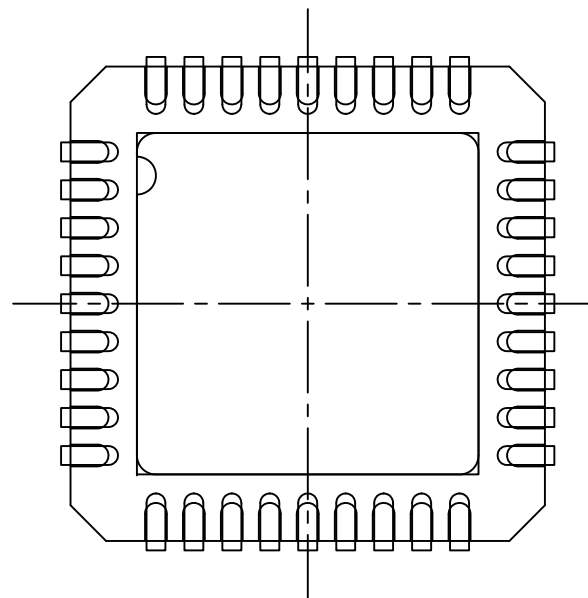
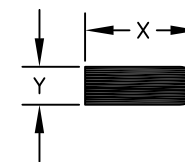


RECOMMENDED LAND PATTERN



PACKAGE OVERLAY

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
X	0.59	0.60	0.61	.023	.024	.024
Y	0.19	0.20	0.21	.007	.008	.008



PAD DETAIL INFORMATION

NOTES:

1. REFERENCE PKG. OUTLINE: 21-1030
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. ALL DIMENSIONS APPLY TO PbfREE (+) PKG. CODE ONLY.
4. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.

This document is subject to change without notice.

Contact technical support at <http://www.maximintegrated.com/support> for further questions.

TITLE:  
PACKAGE LAND PATTERN,  
[G3655+1] PUNCH QFN

APPROVAL

DOCUMENT CONTROL NO.  
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REV. A

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